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(57)

ABSTRACT

A memory device includes a device housing, a memory module, and a cooling unit. The memory module is disposed in the device housing, wherein the memory module generates heat, and the heat is transmitted to the device housing. The cooling unit is thermally connected to the device housing to dissipate some of the heat. The cooling unit includes a unit housing and a working fluid. An interior space is formed in the unit housing. The working fluid is disposed in the interior space, wherein some of the heat travels from the device housing, passes through the unit housing, and is transmitted to the working fluid.

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